



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-11-17
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC10H065B-TR	7ZDP*3D091T6	A	3068	2017-11-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	320.00	mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.11	Die/Leadframe	338
Lead	2.43	Soft solder	7606
Cobalt	0.46	Leadframe	1444
Antimony trioxide	1.76	Mold compound	5500

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7ZDP*3D091T6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other Organic Materials	4.243	mg	supplier	die	Silicium carbide	409-21-2		4.142	mg	976196	12944
				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	5656	75
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	942	13
				supplier	metallization	Silver (Ag)	7440-22-4		0.041	mg	9663	128
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	236	3
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	236	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	943	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.016	mg	3771	50
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.010	mg	2357	31
				supplier								
Leadframe	Copper & its alloys	165.043	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	994601	512975
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1999	1031
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2799	1444
				supplier	metallization	Nickel (Ni)	7440-02-0		0.092	mg	559	288
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	22
				supplier								
Soft solder	Solder	2.549	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.434	mg	954884	7606
				supplier	solder	Silver (Ag)	7440-22-4		0.064	mg	25108	200
				supplier	solder	Tin (Sn)	7440-31-5		0.051	mg	20008	159
Bonding wires	Other inorganic materials	0.831	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.831	mg	1000000	2597
Encapsulation	Other Organic Materials	146.289	mg	supplier	mold compound	Silica, vitreous	60676-86-0		117.909	mg	806000	368466
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		10.240	mg	69998	32000
				supplier	mold compound	Phenol resin	9003-35-4		5.852	mg	40003	18288
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		8.777	mg	59998	27428
				supplier	mold compound	Antimony Trioxide	1309-64-4		1.756	mg	12004	5486
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		1.024	mg	7000	3200
				supplier	mold compound	Carbon black	1333-86-4		0.731	mg	4997	2284
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266